

/ Descriptions

/ Features

$V_{GS} = 0.53 \text{ V}$ $I_{DS} = 0.31 \text{ A}$
 $U_{GS} = 0.718 \text{ V} \leq 853 \text{ m}\Omega + W_{DS} 1733 \text{ m}\Omega$,
 $U_{GS} = 0.518 \text{ V} \leq ; 3 \text{ m}\Omega + W_{DS} 18 : 3 \text{ m}\Omega$,
 $U_{GS} = 0.41 \text{ V} \leq 4433 \text{ m}\Omega + W_{DS} 1 : 43 \text{ m}\Omega$,
 5 NV HVG $srrwhfwhg$ xs wr 5 NV !
 KI $Srrgxfwl$

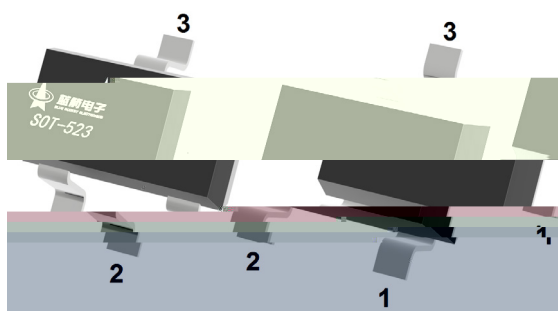
/ Applications

GF2GF

/ Equivalent Circuit

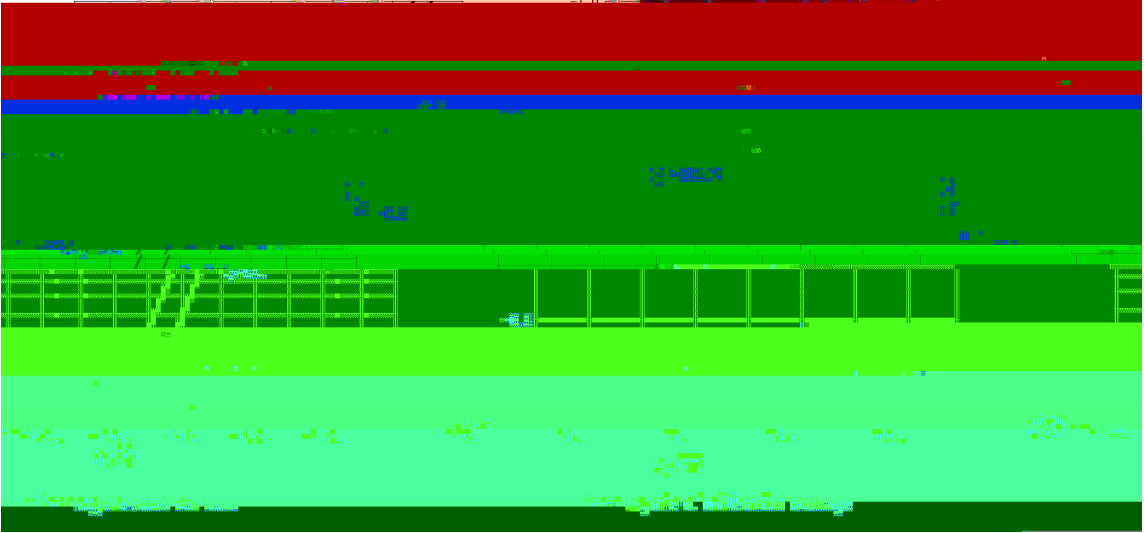
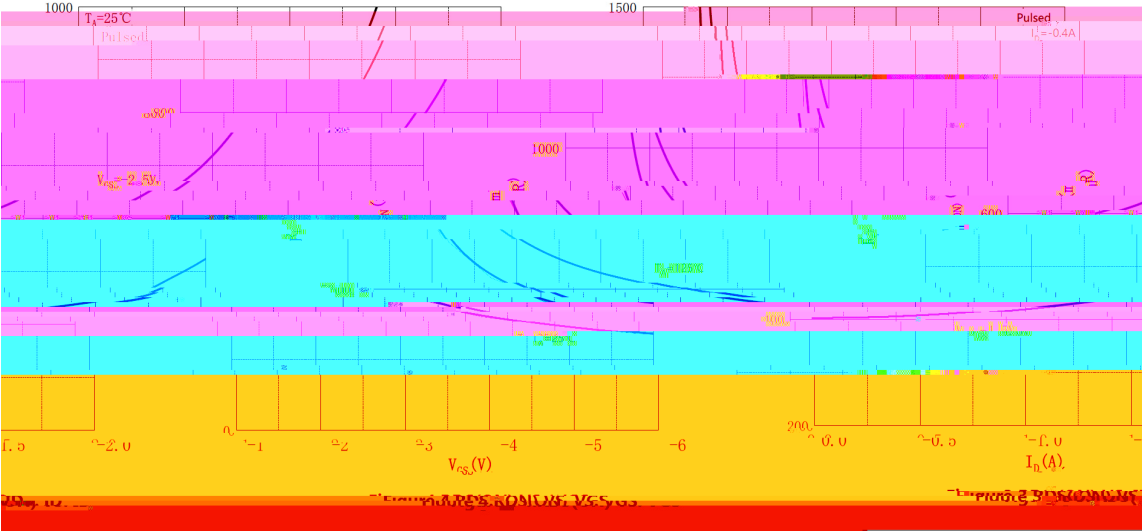
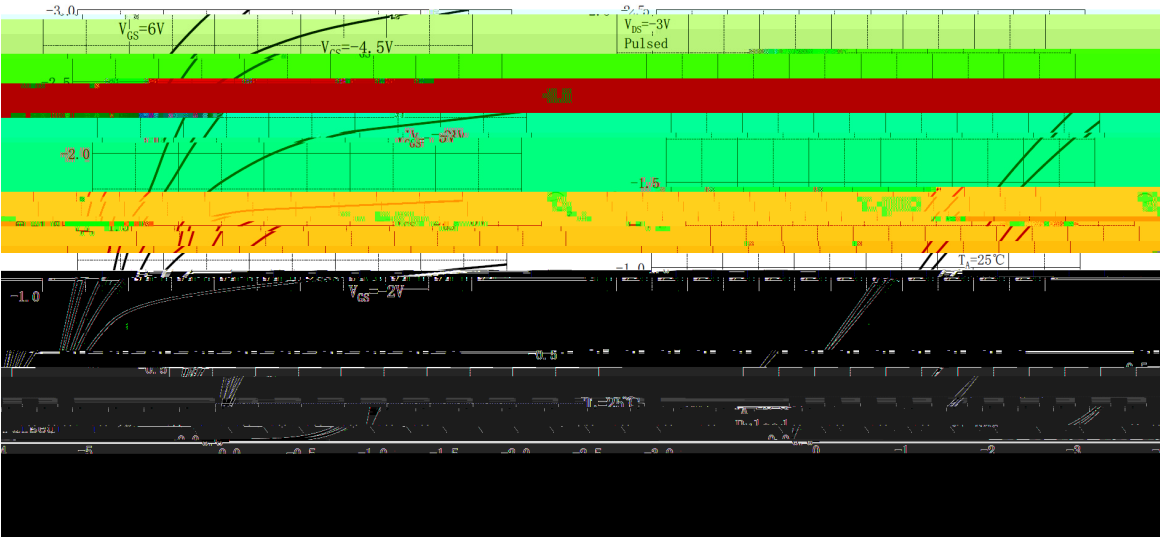


/ Pinning

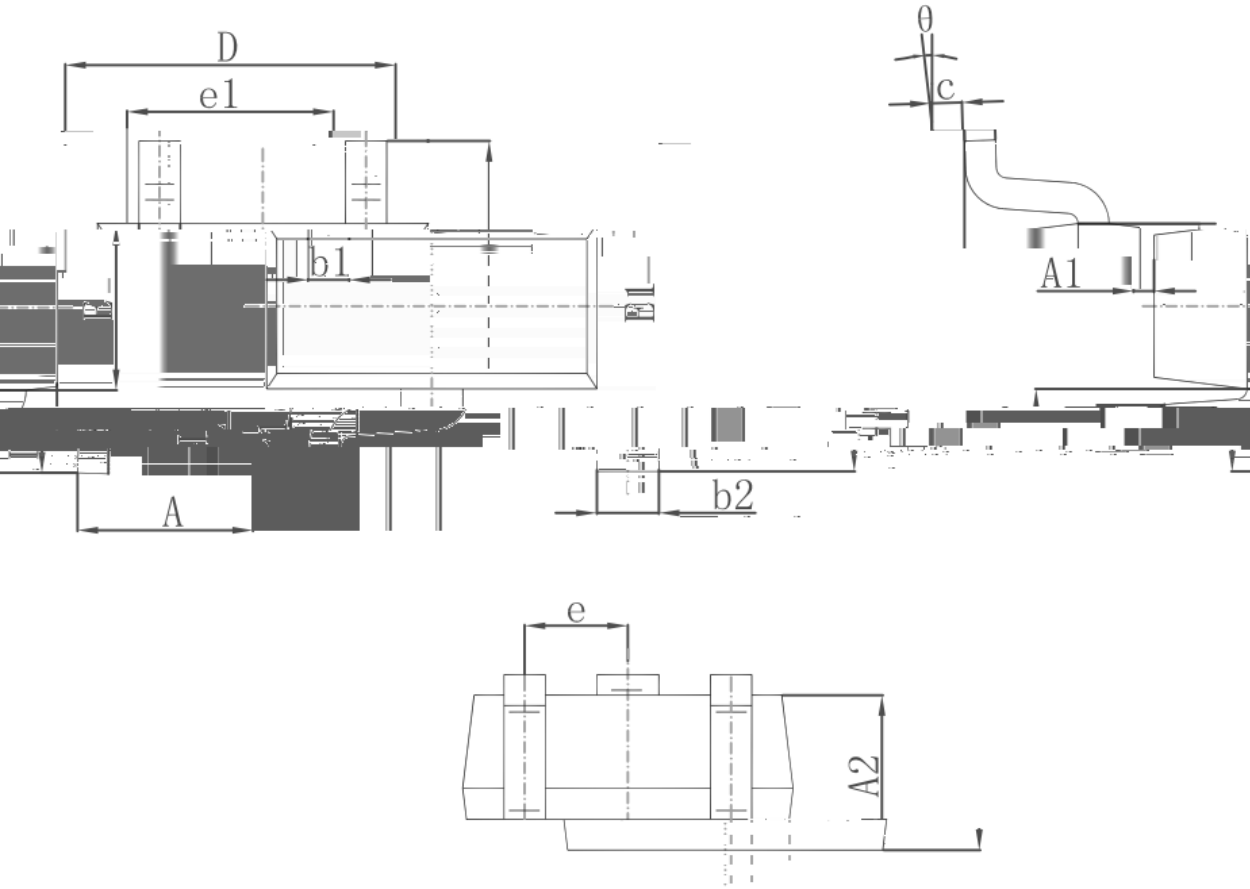


/ Marking

/ Electrical Characteristic Curve

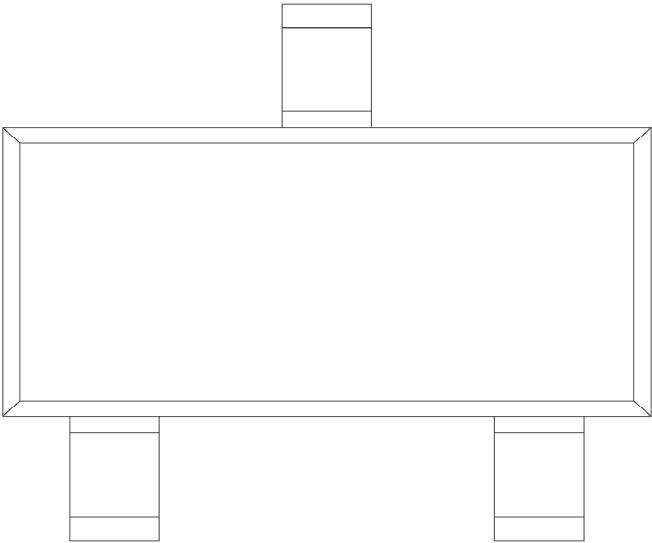


/ Package Dimensions



Dimensions In Inches		Symbol	Dimensions In Millimeters		Dimensional Callouts
Min.	Max.		Min.	Max.	
0.028	0.035	A	0.700	0.900	0.028
0.031	0.035	A1	0.700	0.800	0.028
0.031	0.035	A2	0.700	0.800	0.028
0.031	0.035	b1	0.700	0.800	0.028
0.031	0.035	b2	0.700	0.800	0.028
0.008	0.008	c	0.200	0.200	0.004
0.007	0.007	D	0.700	1.700	0.028
0.069	0.069	e	1.450	1.750	0.057
0.020 TYP.	0.020 TYP.	e1	0.500 TYP.	0.500 TYP.	0.035
0.043	0.043	L	0.900	1.100	0.035
0.016 REF.	0.016 REF.	L1	0.400 REF.	0.400 REF.	0.010
0.018	0.018	L1	0.260	0.460	0.010
8°	8°	theta	0°	8°	0°

/ Marking Instructions



() / Temperature Profile for IR Reflow Soldering(Pb-Free)

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/ Resistance to Soldering Heat Test Conditions

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/ Packaging SPEC.